Complete set of claims

1(original). A composition for cleaning a positive or negative photoresist which comprises (a) from 0.1 to 20 wt. % of an alkyl oxide polymer with a molecular weight of from 50 to 2000; and (b) from 80 to 99.9 wt. % of an organic solvent containing from 1 to 20 parts by weight of dipropylene glycol alkyl ether (DPGAE), from 10 to 50 parts by weight of N-methyl pyrolidone (NMP) and from 50 to 90 parts by weight of methyl isobutyl ketone (MIBK).

2(original). The composition for cleaning a positive or negative photosensitive material of claim 1, wherein the alkyl oxide polymer is ethylene oxide polymer.

3(original). The composition for cleaning a positive or negative photosensitive material of claim 1, wherein the alkyl oxide polymer is propylene oxide polymer.

4(currently amended). The composition for cleaning a positive or negative photosensitive material of any one of claims 1 to 3 claim 1, wherein the dipropylene glycol alkylether is dipropylene glycol methyl ether.

5(original). A composition for cleaning a positive or negative photoresist which comprises (a) from 0.1 to 20 wt. % of an alkyl oxide polymer with a molecular weight of from 50 to 2000; and (b) from 80 to 99.9 wt. % of an organic solvent containing from 10 to 90 parts by weight of dimethyl formamide (DMF) ordimethylacetamide(DMAc) and from 10 to 50 parts by weight of n-butyl acetate.

6(original). The composition for cleaning a positive or negative photosensitive material of claim 5, wherein the alkyl oxide polymer is ethylene oxide polymer.

7(original). The composition for cleaning a positive or negative photosensitive material of claim 5, wherein the alkyl oxide polymer is propylene oxide polymer.

- 8. (New) A process for cleaning a positive or negative photoresist which comprises,
 - a) forming a coating of the photoresist on a substrate; and,
- b) removing the photoresist from peripheral area using the composition from claim 1.
- 9. (New) A device comprising a fine circuit made from the process of claim 8.
- 10. (New) A process for cleaning a positive or negative photoresist which comprises,
 - a) forming a coating of the photoresist on a substrate; and,
- b) removing the photoresist from peripheral area using the composition from claim 5.
- 11. (New) A device comprising a fine circuit made from the process of claim 10.